

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Bi-directional TVS Array for High-Speed Data Line Protection

The SMDA05C transient voltage suppressor series is designed to protect equipment attached to up to four high speed communication lines from ESD, EFT, and lightning.

Features:

- SO-8 Package
- Peak Power 300 W 8 x 20 μS
- ESD Rating:

IEC 61000-4-2 (ESD) ±15 kV (air) ±8 kV (contact)

IEC 61000-4-4 (EFT) 40 A (5/50 ns)

IEC 61000-4-5 (lightning) 12 A (8/20 μs)

- UL Flammability Rating of 94 V-0
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications:

- High Speed Communication Line Protection
- Data and I/O Lines
- Microprocessor Based Equipment
- LAN/WAN Equipment
- Servers
- Notebook and Desktop PC
- Serial and Parallel Ports
- Peripherals

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--|-----------------------------------|----------------|------|
| Peak Power Dissipation 8 x 20 μs @ T _A = 25°C (Note 1) | P _{pk} | 300 | W |
| Junction and Storage Temperature Range | T _J , T _{stg} | -55 to +150 | °C |
| Lead Solder Temperature – Maximum 10 Seconds Duration | TL | 260 | °C |

1

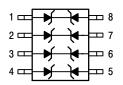


ON Semiconductor®

http://onsemi.com

SO-8 VOLTAGE SUPPRESSOR 300 WATTS PEAK POWER

PIN CONFIGURATION AND SCHEMATIC





SO-8 CASE 751

MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week

■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 3 of this data sheet.

^{1.} Non-repetitive current pulse 8 x 20 μS exponential decay waveform

SMDA05C ELECTRICAL CHARACTERISTICS

| Characteristic | Symbol | Min | Тур | Max | Unit |
|---|------------------|-----|-----|-----|------|
| Reverse Working Voltage | V _{RWM} | - | - | 5.0 | V |
| Reverse Breakdown Voltage @ I _t = 1.0 mA | V _{BR} | 6.0 | - | - | V |
| Reverse Leakage Current @ V _{RWM} = 5 Volts | I _R | N/A | - | 20 | μΑ |
| Maximum Clamping Voltage @ I _{PP} = 1.0 A, 8 x 20 μs | V _C | N/A | - | 9.8 | V |
| Maximum Clamping Voltage @ I _{PP} = 5.0 A, 8 x 20 μs | V _C | N/A | - | 11 | V |
| Maximum Peak Pulse Current, 8 x 20 μs | I _{PP} | - | - | 17 | Α |
| Junction Capacitance @ V _R = 0 V, f = 1 MHz | CJ | - | - | 350 | pF |

SMDA12C ELECTRICAL CHARACTERISTICS

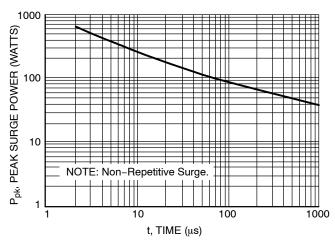
| Characteristic | Symbol | Min | Тур | Max | Unit |
|---|-----------------|------|-----|-----|------|
| Reverse Working Voltage | V_{RWM} | - | - | 12 | V |
| Reverse Breakdown Voltage @ I _t = 1.0 mA | V _{BR} | 13.3 | - | = | V |
| Reverse Leakage Current @ V _{RWM} = 12 Volts | I _R | N/A | - | 1.0 | μΑ |
| Maximum Clamping Voltage @ I _{PP} = 1.0 A, 8 x 20 μs | V _C | N/A | - | 19 | V |
| Maximum Clamping Voltage @ I _{PP} = 5.0 A, 8 x 20 μs | V _C | N/A | - | 24 | V |
| Maximum Peak Pulse Current, 8 x 20 μs | I _{PP} | - | - | 12 | Α |
| Junction Capacitance @ V _R = 0 V, f = 1 MHz | CJ | - | - | 120 | pF |

SMDA15C ELECTRICAL CHARACTERISTICS

| Characteristic | Symbol | Min | Тур | Max | Unit |
|---|------------------|------|-----|-----|------|
| Reverse Working Voltage | V _{RWM} | - | - | 15 | V |
| Reverse Breakdown Voltage @ I _t = 1.0 mA | V _{BR} | 16.7 | - | = | V |
| Reverse Leakage Current @ V _{RWM} = 15 Volts | I _R | N/A | - | 1.0 | μΑ |
| Maximum Clamping Voltage @ I _{PP} = 1.0 A, 8 x 20 μs | V _C | N/A | - | 24 | V |
| Maximum Clamping Voltage @ I _{PP} = 5.0 A, 8 x 20 μs | V _C | N/A | - | 30 | V |
| Maximum Peak Pulse Current, 8 x 20 μs | I _{PP} | - | - | 10 | Α |
| Junction Capacitance @ V _R = 0 V, f = 1 MHz | CJ | _ | _ | 75 | pF |

SMDA24C ELECTRICAL CHARACTERISTICS

| Characteristic | Symbol | Min | Тур | Max | Unit |
|---|------------------|------|-----|-----|------|
| Reverse Working Voltage | V _{RWM} | - | - | 24 | V |
| Reverse Breakdown Voltage @ I _t = 1.0 mA | V _{BR} | 26.7 | - | = | V |
| Reverse Leakage Current @ V _{RWM} = 24 Volts | I _R | N/A | - | 1.0 | μА |
| Maximum Clamping Voltage @ I _{PP} = 1.0 A, 8 x 20 μs | V _C | N/A | - | 43 | V |
| Maximum Clamping Voltage @ I _{PP} = 5.0 A, 8 x 20 μs | V _C | N/A | - | 55 | V |
| Maximum Peak Pulse Current, 8 x 20 μs | I _{PP} | - | - | 5.0 | Α |
| Junction Capacitance @ V _R = 0 V, f = 1 MHz | CJ | - | - | 50 | pF |



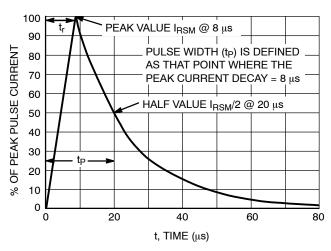


Figure 1. Pulse Width

Figure 2. $8 \times 20 \mu s$ Pulse Waveform

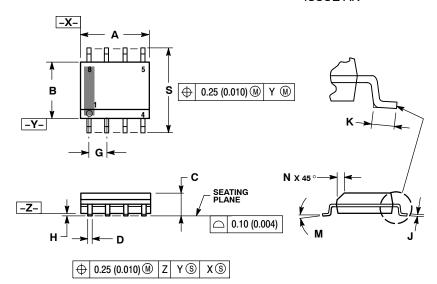
ORDERING INFORMATION

| Device | Marking | Package | Shipping [†] |
|-------------|---------|-------------------|-----------------------|
| SMDA05CDR2G | AAA | SO-8 (Pb-Free) | 2500 / Tape & Reel |
| SMDA12CDR2G | AAC | SO-8 (Pb-Free) | 2500 / Tape & Reel |
| SMDA15CDR2G | AAD | SO-8 (Pb-Free) | 2500 / Tape & Reel |
| SMDA24CDR2G | AAE | SO-8 (Pb-Free) | 2500 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

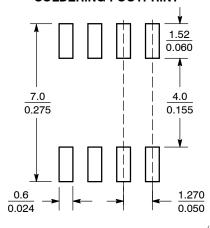
SOIC-8 NB CASE 751-07 **ISSUE AK**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

| | MILLIMETERS | | INCHES | |
|-----|-------------|----------|--------|-------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 4.80 | 5.00 | 0.189 | 0.197 |
| В | 3.80 | 4.00 | 0.150 | 0.157 |
| С | 1.35 | 1.75 | 0.053 | 0.069 |
| D | 0.33 | 0.51 | 0.013 | 0.020 |
| G | 1.27 | 1.27 BSC | | 0 BSC |
| Н | 0.10 | 0.25 | 0.004 | 0.010 |
| J | 0.19 | 0.25 | 0.007 | 0.010 |
| K | 0.40 | 1.27 | 0.016 | 0.050 |
| М | 0 ° | 8 ° | 0 ° | 8 ° |
| N | 0.25 | 0.50 | 0.010 | 0.020 |
| S | 5.80 | 6.20 | 0.228 | 0.244 |

SOLDERING FOOTPRINT*



(mm) SCALE 6:1

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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